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(57) Abstract:

wafer and prevention of particles from sticking by forming a titanium oxide film of a specific composition on the dimensional retention accuracy for a surface of a silicon nitride or sialon obtain a member, useful as the one PROBLEM TO BE SOLVED: To suppression of damage to a silicon stress and a temperature changes, semiconductors and excellent in used in a production process for

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expansion coefficient as a substrate having a specific average thermal and composing the member.

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adding a sintering assistant, e.g. Y203, A1203 or MgO in the total amount of film is composed by forming a TiO2-x and TiO2 having the thickness of preferably ≤1% that of silicon nitride thermal expansion coefficient between (2>(x)>0] film or a film comprising a SOLUTION: This ceramic composite and sintering the resultant mixture by ≤15% to the silicon nitride or sialon dense sintered compact, obtained by sintering and having \geq 95% relative sintering or hot isostatic press (HIP) density and ≤1.5×10-6/°C average atmospheric sintering, gas pressure mixture composition of the TiO2-x or sialon as a substrate which is a 20 and 50°C on the surface of the

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